



### Features

- Small Body Outline Dimensions:  
0.60 mm x 0.30 mm
- Bidirectional ESD Protection of one line
- Low Clamping Voltage
- Low Capacitance: 3 pF
- Working Voltage: 5 V
- Low Leakage Current

### IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) ±8kV (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 3.5A (8/20µs)

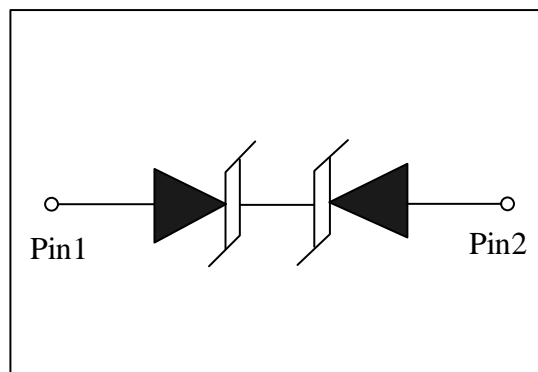
### Mechanical Characteristics

- DFN0603-2L package
- Molding compound flammability rating:  
UL 94V-0
- Marking: Marking Code
- Packaging: Tape and Reel per EIA 481
- RoHS Compliant

### Applications

- Cellular handsets and accessories
- Portable electronics
- Communication systems
- Computers and peripherals

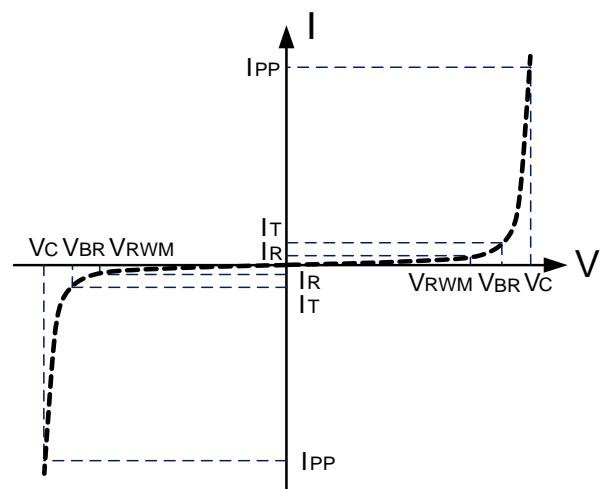
### Schematic & PIN Configuration



Absolute Maximum Rating			
Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p = 8/20\mu s$ )	$P_{PP}$	50	W
Peak Pulse Current ( $t_p = 8/20\mu s$ )	$I_{pp}$	3.5	A
Operating Temperature	$T_J$	-55 to + 125	°C
Storage Temperature	$T_{STG}$	-55 to +150	°C

## Electrical Parameters (T=25°C)

Symbol	Parameter
$I_{PP}$	Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Reverse Stand-Off Voltage
$I_R$	Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current



## Electrical Characteristics

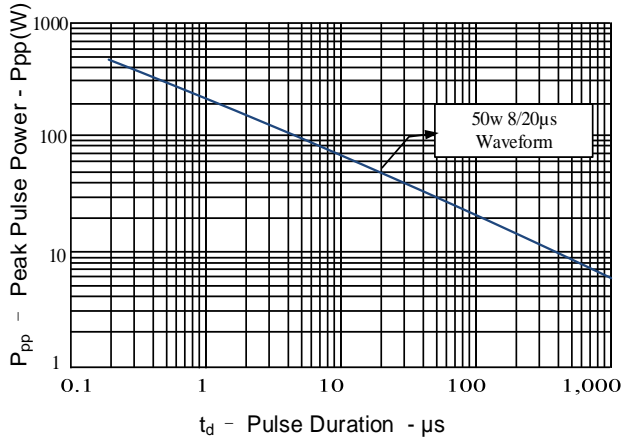
DW05DLCS-B-01-E						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	$V_{RWM}$				5.0	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T=1mA$	5.5		9.5	V
Reverse Leakage Current	$I_R$	$V_{RWM}=5V, T=25^\circ C$			100	nA
Clamping Voltage	$V_C$	$I_{PP}=3.5A, t_p=8/20\mu s$			13.5	V
Dynamic Resistance <sup>1,2</sup>	$R_{DYN}$	TLP=0.2/100ns		0.3		$\Omega$
ESD Clamping Voltage <sup>1</sup>	$V_C$	$I_{PP} = 4A,$ $t_p = 0.2/100ns$ (TLP)		6.5		V
ESD Clamping Voltage <sup>1</sup>	$V_C$	$I_{PP} = 16A,$ $t_p = 0.2/100ns$ (TLP)		10.3		V
Junction Capacitance	$C_j$	$V_R = 0V, f = 1MHz$		3	3.5	pF

Notes : 1、 TLP Setting :  $t_p=100ns, t_r=0.2ns, I_{TLP}$  and  $V_{TLP}$  sample window: $t_1=70ns$  to  $t_2=90ns$ .

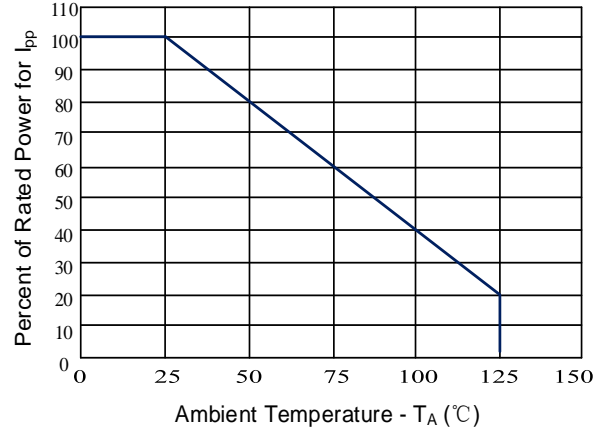
2、 Dynamic resistance calculated from  $I_{PP}=4A$  to  $I_{PP}=16A$  using "Best Fit".

# Typical Characteristics

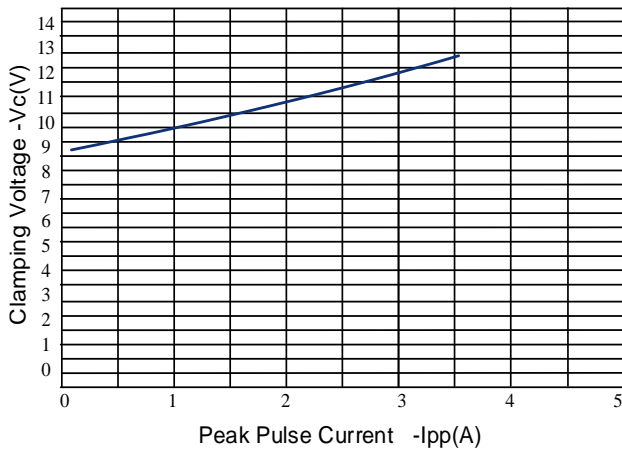
**Figure 1: Peak Pulse Power vs. Pulse Time**



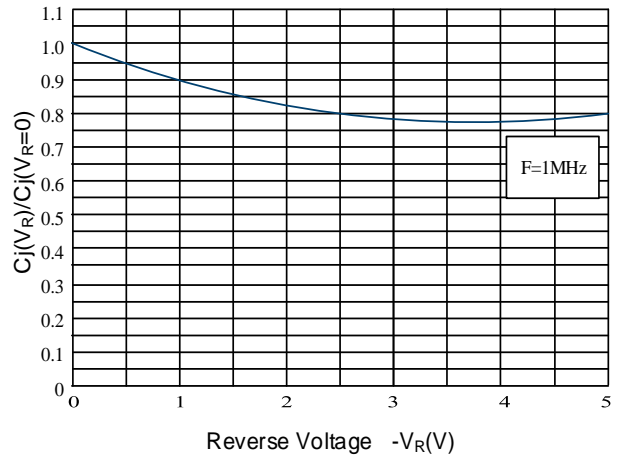
**Figure 2: Power Derating Curve**



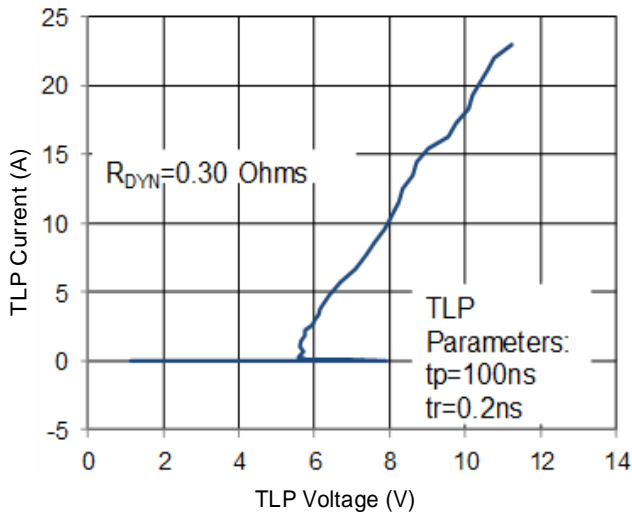
**Figure 3: Clamping Voltage vs. Peak Pulse Current**



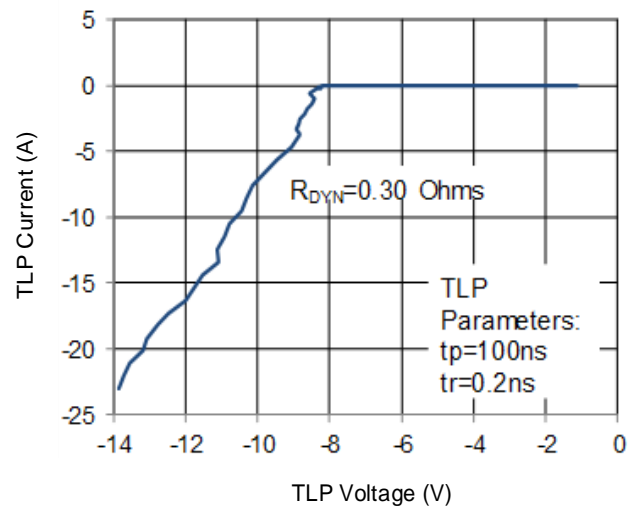
**Figure 4: Normalized Junction Capacitance vs. Reverse Voltage**



**Figure 5: TLP Positive I-V Curve**

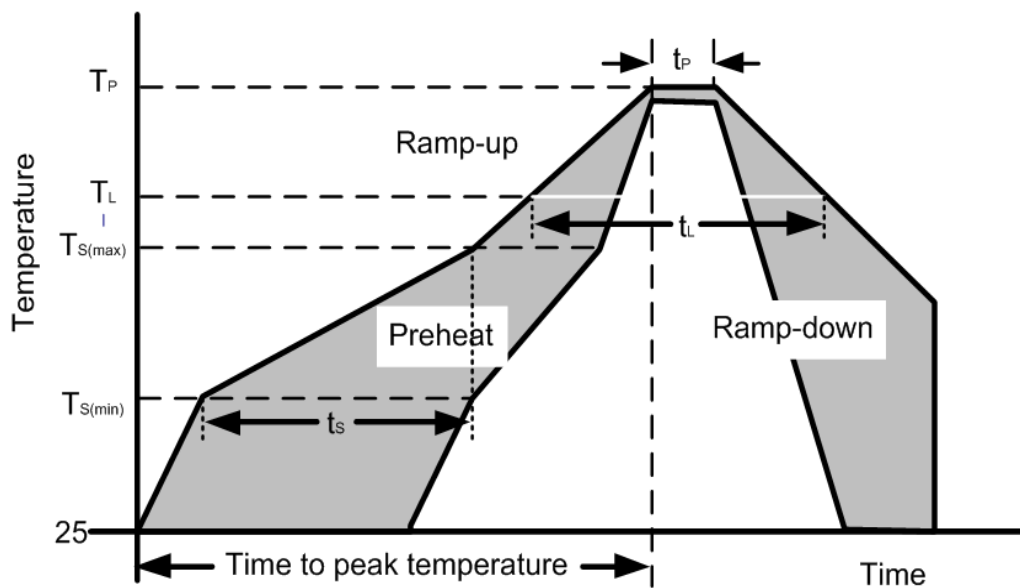


**Figure 6: TLP Negative I-V Curve**



## Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ( $T_{S(min)}$ )	150°C
	Temperature Max ( $T_{S(max)}$ )	200°C
	Time (min to max) ( $t_s$ )	60 – 190 secs
Average ramp up rate (Liquidus Temp) ( $T_L$ ) to peak		5°C/second max
$T_{S(max)}$ to $T_L$ —Ramp-up Rate		5°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Temperature ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_P$ )		260+0/-5 °C
Time within actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature ( $T_P$ )		8 minutes Max.
Do not exceed		280°C



# Outline Drawing –DFN0603-2L

### PACKAGE OUTLINE

TOP VIEW

BOTTOM VIEW

SIDE VIEW

**DFN0603-2L**

SYMBOL	MILIMETER	
	MIN	MAX
A	0.28	0.32
A1	0.00	0.05
b1	0.13	0.23
b2	0.14	0.24
c	0.05	0.15
D	0.55	0.65
e	0.350BSC	
L1	0.030BSC	
L2	0.025BSC	
L3	0.035BSC	
E	0.25	0.35
L	0.20	0.30
h	0.00	0.10

### Land Pattern

### Marking Codes

Part Number	Marking Code
DW05DLCS-B-01-E	PIN 1  C = Specific Device Code M = Month Code

### Package Information

Qty: 15k/Reel